

CBCS SCHEME

USN

15NT73

Seventh Semester B.E. Degree Examination, Dec.2019/Jan.2020
MEMS & NEMS

Time: 3 hrs.

Max. Marks: 80

Note: Answer FIVE full questions, choosing ONE full question from each module.

Module-1

- 1 a. Discuss the steps involved in fabrication of IC's. (08 Marks)
b. Explain the working principle of piezo resistive sensors and piezo ink jet printer. (08 Marks)

OR

- 2 a. Explain the 4 types of MEMS packages. (08 Marks)
b. Enumerate the concept of miniaturization and list the benefits. (08 Marks)

Module-2

- 3 a. Write a note on Acoustic wave transducers. (08 Marks)
b. Define transducer. Explain the working of capacitive transducers. (08 Marks)

OR

- 4 a. Explain the importance of Cantilever based transducer. (08 Marks)
b. Explain the working principle,
 (i) Electrochemical transducer.
 (ii) Bipolar junction transducer. (08 Marks)

Module-3

- 5 a. List and explain the various etching methods. (08 Marks)
b. Describe the thin film techniques and give the applications. (08 Marks)

OR

- 6 a. Explain sputtering process and short list its application. (08 Marks)
b. Explain the concept of epitaxial growth and give its types. (08 Marks)

Module-4

- 7 a. Explain the concept of reliability and stability. (08 Marks)
b. Enumerate the concept of, (i) CMOS (ii) Transmitters (08 Marks)

OR

- 8 a. Define packaging and explain the various packaging techniques. (08 Marks)
b. Discuss the working of signal amplifiers and signal conditioning. (08 Marks)

Module-5

- 9 a. Define NEMS. Explain Nano machining of NEMS. (08 Marks)
b. Explain briefly about future challenges and applications of NEMS. (08 Marks)

OR

- 10 a. Write short note on stencil lithography and sacrificial etching. (08 Marks)
b. Discuss about Focused ion beam doping and with respect to chemical etching. (08 Marks)

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